

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. – 14. (Cancelled)

15. (Previously Presented) A method of manufacturing a circuit board comprising:

a step of mounting a first component on a substrate by a solder connection;

a step of arranging an anisotropic conductive film within a band region of a surface of the substrate;

a step of arranging a second component on the anisotropic conductive film; and

a step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween;

wherein said step of arranging said anisotropic conductive film within said band region of said substrate is performed after said step of mounting the first component on said substrate by the solder connection;

said step of thermocompression-bonding is performed with a compression bonding head; and

the band region is wider than the head.

16. (Previously Presented) A method of manufacturing a circuit board according to claim 15, wherein said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.

17. – 20. (cancelled)

21. (Previously Presented) A method of manufacturing a circuit board in which components are mounted thereto, comprising:

a.) selecting a band region on a surface of the circuit board;  
b.) soldering a first component onto the circuit board outside of the band region; and

c.) after step b.), mounting a second component on the substrate within the band region with an anisotropic conductive film,

wherein step c.) includes a step of thermocompression-bonding the second component to said substrate with a compression bonding head; and  
the band region is wider than the head.

22. (Previously Presented) The method of claim 21 where step c.) is performed with a heated compression bonding head, and

wherein the band region is selected to correspond generally to the areas over which the head travels during step c.) thereby preventing impact of the head with the first component and isolating the first component from the heat generated by the head.

23. (Previously Presented) The method of claim 15, wherein the first component is selected from the group of passive and mechanical components, and the second component comprises a semiconductor device.

24. (Cancelled)

25. (Previously Presented) The method of claim 15, wherein alignment marks are provided outside the band region.

26. (Previously Presented) The method of claim 15, wherein the bonding region is selected by performing a solder reflow process.

27. (Previously Presented) The method of claim 15, wherein the band region divides a first set of first components on one part of the substrate and a second set of first components on a second part of the substrate.

28. (Previously Presented) The method of claim 23, wherein the second component is selected from the group of a power source IC and a power source LSI.

29. (Previously Presented) The method of claim 15, wherein the band region extends from one end of the substrate to another end of the substrate.

30. (Previously Presented) The method of claim 15, wherein the band region extends rectilinearly along the substrate.

31. (Previously Presented) The method of claim 15, further comprising:  
forming wiring patterns on the substrate in the band region.

32. (Previously Presented) The method of claim 15, further comprising:  
forming a dummy electrode at a position associated with the second component.

33. (Cancelled)

34. (Cancelled)

35. (New) A method of manufacturing a circuit board comprising:  
a step of mounting a plurality of first components within first regions on a surface of a substrate by a solder connection;  
a step of arranging an anisotropic conductive film on a predetermined position of the substrate;  
a step of arranging a second component on the anisotropic conductive film; and  
a step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween with a compression bonding head;

wherein said step of arranging said anisotropic conductive film on the predetermined position of said substrate is performed after said step of mounting the first components on said substrate by the solder connection;

the substrate includes a band region that extends between the first regions; and  
the band region includes the second component other than the first component,  
the band region extending along a longitudinal direction of a pressing surface of the compression bonding head.